



Final Product/Process Change Notification

Document #:FPCN25133X

Issue Date:16 May 2023

Title of Change:	WDFN6L Clip Transfer from Cebu to Seremban.	
Proposed First Ship date:	23 Aug 2023 or earlier if approved by customer	
Contact Information:	Contact your local onsemi Sales Office or saziela.senin@onsemi.com	
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Additional Reliability Data:	Contact your local onsemi Sales Office or MohdAzizi.Azman@onsemi.com	
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com	
Marking of Parts/ Traceability of Change:	Material will be traceable with onsemi lot trace code and tracking	
Change Category:	Assembly Change, Test Change	
Change Sub-Category(s):	Material Change, Manufacturing Site Transfer	
Sites Affected:		
onsemi Sites	External Foundry/Subcon Sites	
onsemi Seremban, Malaysia	None	
Description and Purpose:		
This Final Product Change Notification is to announce that onsemi intends to transfer WDFN6L Clip devices from onsemi Cebu, Philippines to onsemi Seremban, Malaysia.		
	From	To
Lead Frame	ETCHED LEADFRAME, PQFN 2.0X2.0 MM, 6LDS FULL DRAIN	WDFN 2.05X2.05 6L 0.65P WIDE LEADFRAME
Clip	ETCHED CLIPFRAME, PQFN, 2.0 X 2.0 MM POWERCLIP SINGLE	Etch Clip wDFN6L 2.05x2.05 0.65P
Mold Compound	MC GREEN HI CEL9240HF10LS 14MMX6.6G	SUMITOMO EME-G770HM TYPE D
BGBM (Back grind back metal) site	Bucheon, Korea	ISMF, Seremban, Malaysia
Assembly Site	onsemi Cebu, Philippines	onsemi Seremban, Malaysia
Test Site	onsemi Cebu, Philippines	onsemi Seremban, Malaysia
There is no product marking change as a result of this change.		



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Reliability Data Summary:

QV DEVICE NAME: NTLJS17D0P03P8ZTAG

RMS: S85779

PACKAGE: WDFN

Test	Specification	Condition	Interval	Results
High Temperature Reverse Bias	JESD22-A108	Ta=150°C, 100% max rated V	1008 hrs	0/231
High Temperature Gate Bias	JESD22-A108	Ta=150°C, 100% max rated Vgss	1008 hrs	0/231
High Temperature Storage Life	JESD22-A103	Ta= Ta=150°C	1008 hrs	0/231
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260 °C, Pre IOL, TC, uHAST, HAST for surface mount pkgs only		0/924
Intermittent Operating Life	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	1000 cyc	0/231
Temperature Cycling	JESD22-A104	Ta= -55°C to +150°C, mount on board	1000 cyc	0/231
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	192 hrs	0/231
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231
Resistance to Solder Heat	JESD22- B106	Ta = 265°C, 10 sec Required for through hole devices only		0/90
Solderability	JSTD002	Ta = 245°C, 5 sec		0/45

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Part Number	Qualification Vehicle
NTLJS3D0N02P8ZTAG	NTLJS17D0P03P8ZTAG
NTLJS7D2P02P8ZTAG	NTLJS17D0P03P8ZTAG
NTLJS17D0P03P8ZTAG	NTLJS17D0P03P8ZTAG